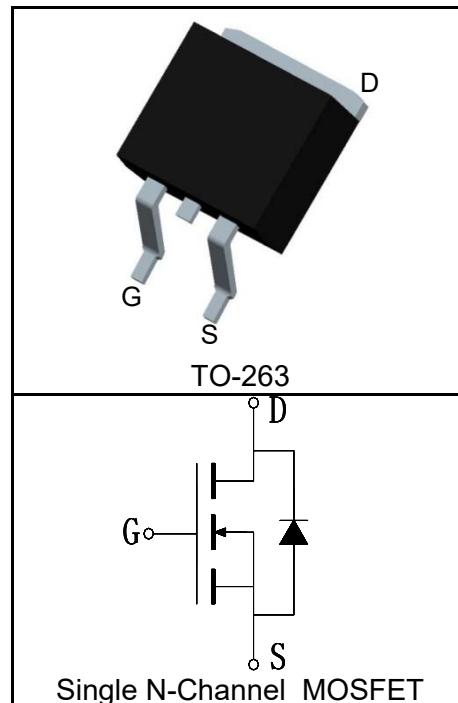


## Features

- 68V/80A,
- $R_{DS\ (ON)} = 7m\Omega$ (Typ.)@ $V_{GS}=10V$
- Low  $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Low Gate Charge
- 100% Avalanche Tested

## Pin Description



## Applications

- DC-DC Converters
- Power Supply



Halogen-Free

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_C=25^\circ C$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	68	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$T_J$	Maximum Junction Temperature	175	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$	A
<b>Mounted on Large Heat Sink</b>			
$I_{DP}^{(1)}$	300 $\mu s$ Pulse Drain Current Tested	$T_C=25^\circ C$	320
$I_D^{(2)}$	Continuous Drain Current( $V_{GS}=10V$ )	$T_C=25^\circ C$	80
		$T_C=100^\circ C$	56
$P_D$	Maximum Power Dissipation	$T_C=25^\circ C$	115
		$T_C=100^\circ C$	57
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.3	$^\circ C/W$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	62.5	$^\circ C/W$
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	380	mJ

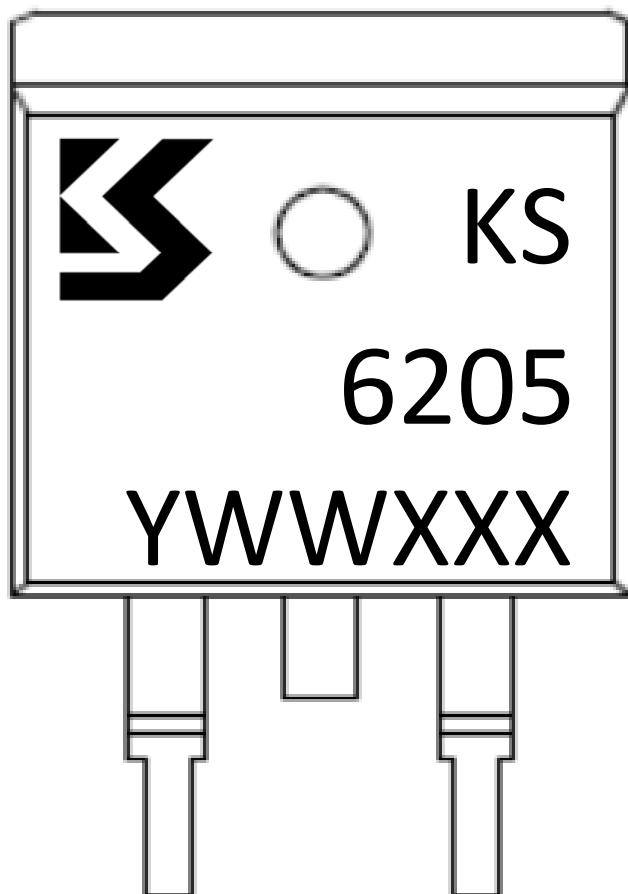
**Electrical Characteristics (T<sub>C</sub>=25°C Unless Otherwise Noted)**

Symbol	Parameter	Test Condition	KS6205GA			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	68			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =68V, V <sub>GS</sub> =0V			1	μA
		T <sub>J</sub> =125°C			30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	2		4	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
R <sub>DS(ON)</sub> <sup>⑤</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		7	8.5	mΩ
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>⑤</sup>	Diode Forward Voltage	I <sub>SD</sub> =40A, V <sub>GS</sub> =0V		0.89	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =40A, dI <sub>SD</sub> /dt=100A/μs		26		ns
Q <sub>rr</sub>	Reverse Recovery Charge			33		nC
<b>Dynamic Characteristics<sup>⑥</sup></b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		1.6		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, Frequency=1.0MHz		2860		pF
C <sub>oss</sub>	Output Capacitance			280		
C <sub>rss</sub>	Reverse Transfer Capacitance			265		
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>DS</sub> =40A, V <sub>GEN</sub> =10V, R <sub>G</sub> =2.5Ω		18		ns
t <sub>r</sub>	Turn-on Rise Time			29		
t <sub>d(OFF)</sub>	Turn-off Delay Time			55		
t <sub>f</sub>	Turn-off Fall Time			27		
<b>Gate Charge Characteristics<sup>⑥</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		77		nC
Q <sub>gs</sub>	Gate-Source Charge			16		
Q <sub>gd</sub>	Gate-Drain Charge			35		

- Notes:
- ①Pulse width limited by safe operating area.
  - ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
  - ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
  - ④Limited by T<sub>Jmax</sub>, I<sub>AS</sub> = 39A, L=0.5mH, V<sub>DD</sub> = 30V, R<sub>G</sub> = 25Ω , Starting T<sub>J</sub> = 25°C.
  - ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
  - ⑥Guaranteed by design, not subject to production testing.

**Ordering and Marking Information**

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS6205GA	TO-263	Tape&Reel	800	13"	24mm

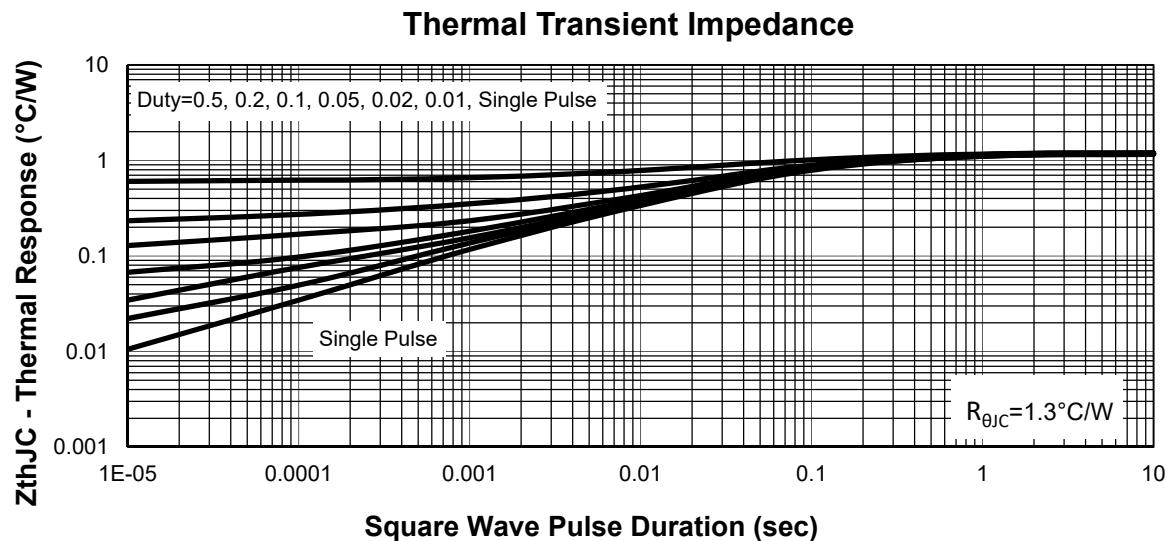
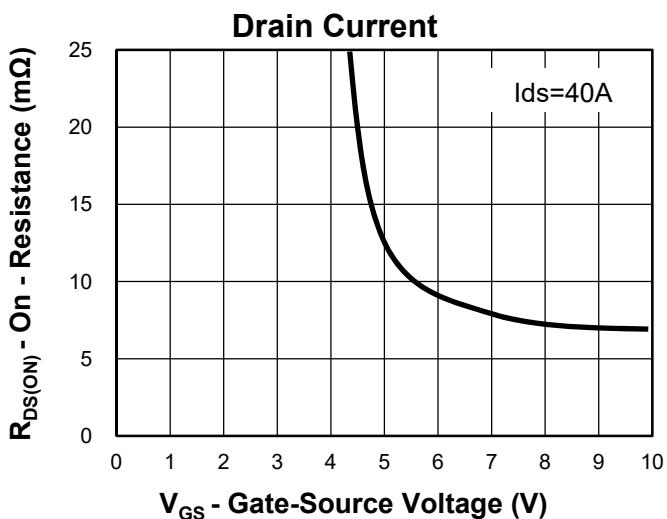
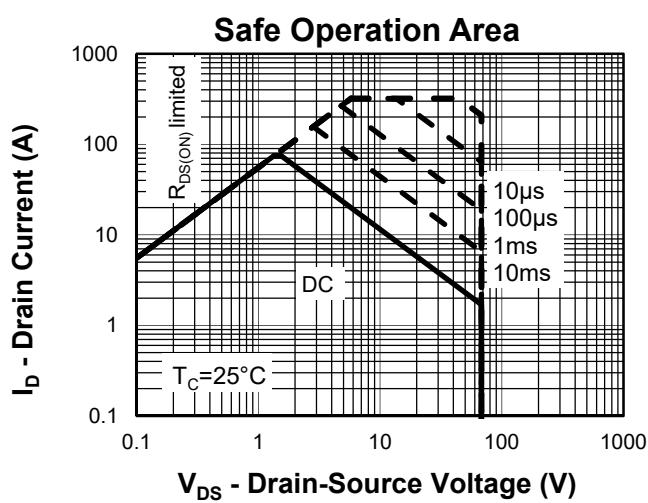
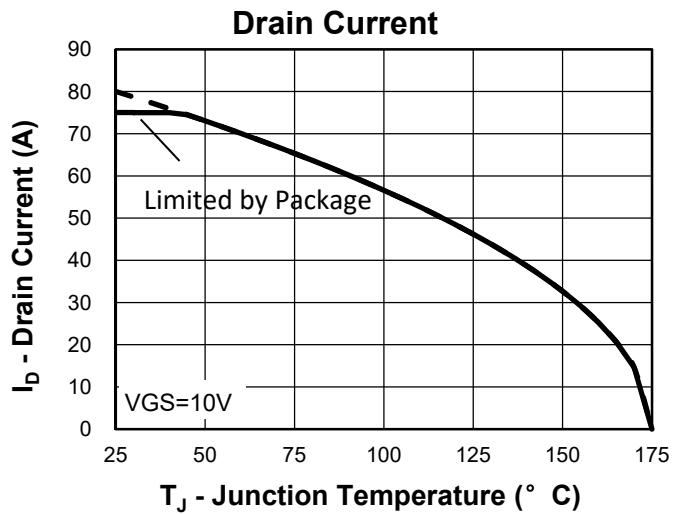
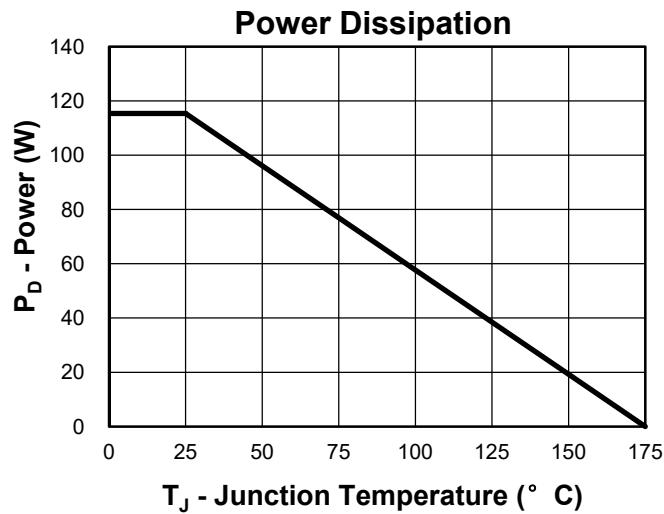


Y =Year, 2017-A, 2018-B,etc.

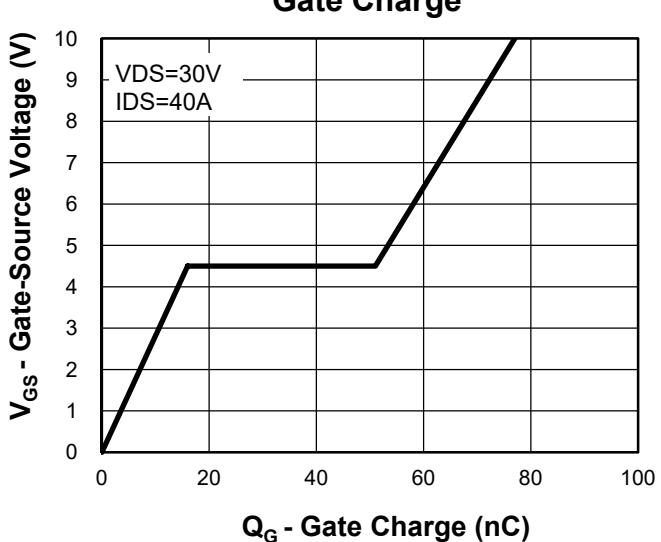
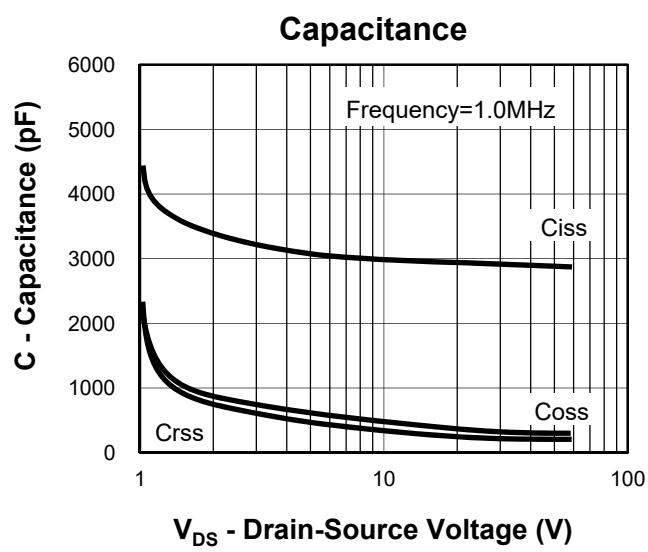
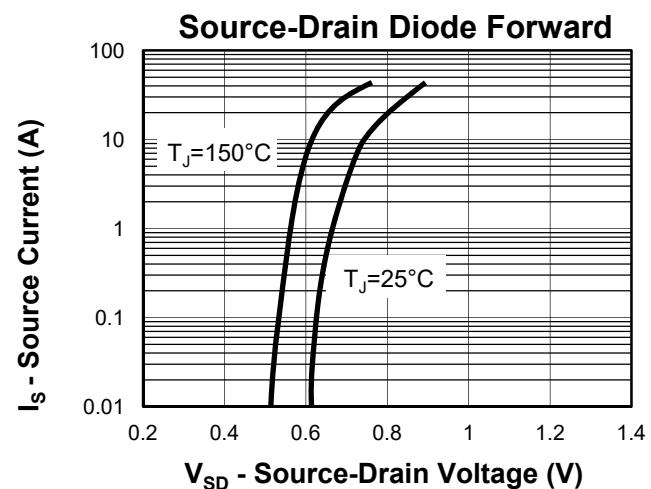
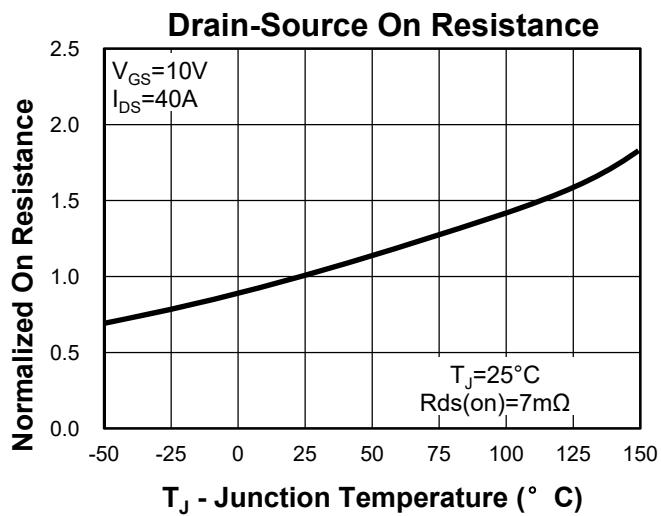
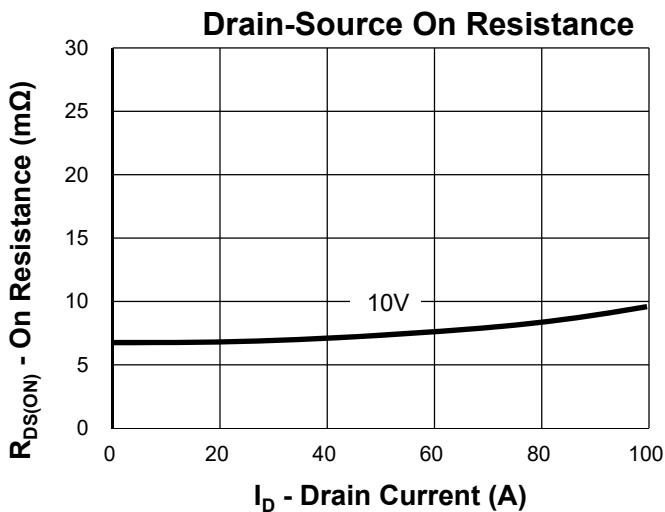
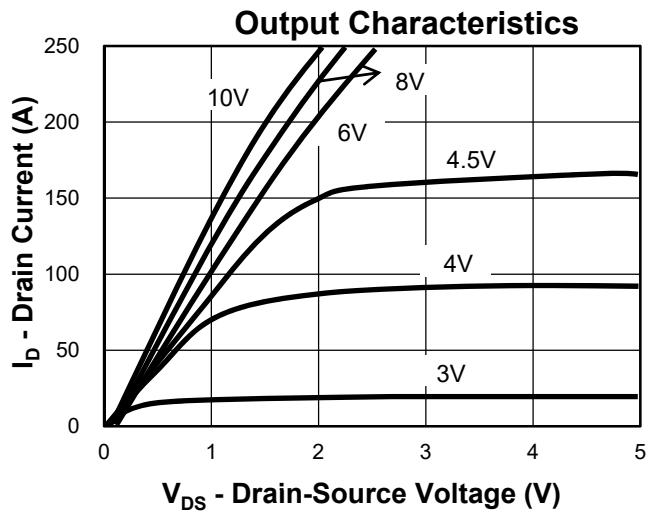
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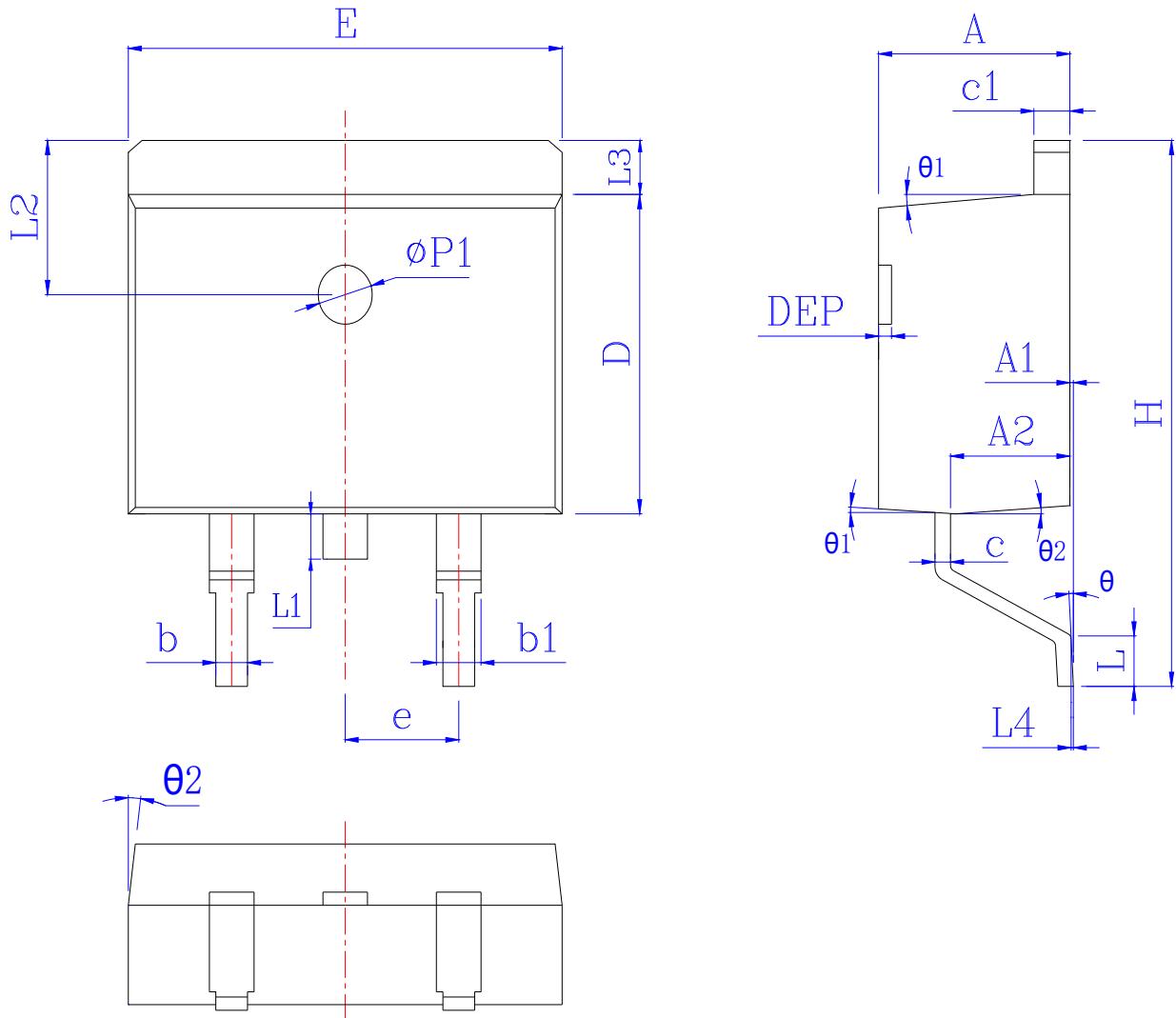
XXX =Lot number.

## Typical Characteristics



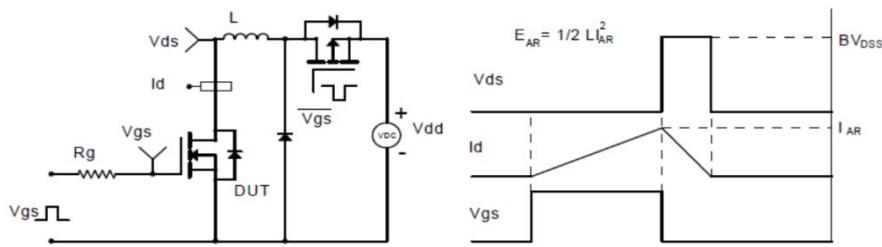
## Typical Characteristics



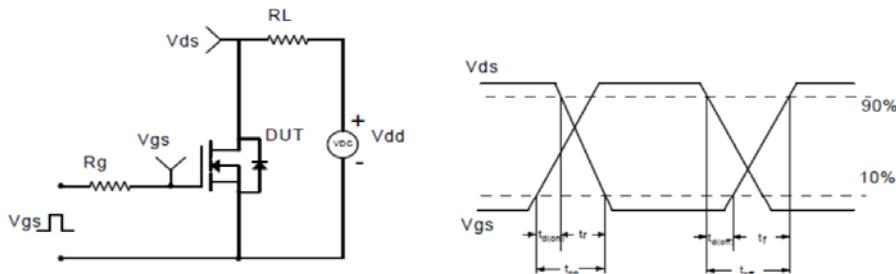
**Package Information**
**TO-263**


SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.55	4.72	0.173	0.179	0.186	L	1.94	2.30	2.60	0.076	0.091	0.102
A1	0.00	0.10	0.25	0.000	0.005	0.010	L3	1.17	1.29	1.40	0.046	0.051	0.055
A2	2.59	2.69	2.79	0.102	0.106	0.110	L1	*	*	1.70	*	*	0.067
b	0.76	*	0.90	0.030	*	0.035	L4	0.25 BSC			0.01 BSC		
b1	1.22	*	1.36	0.048	*	0.054	L2	2.50 REF			0.098 REF		
c	0.33	*	0.47	0.013	*	0.019	$\theta$	$0^\circ$	*	$8^\circ$	$0^\circ$	*	$8^\circ$
c1	1.22	*	1.32	0.048	*	0.052	$\theta_1$	$5^\circ$	$7^\circ$	$9^\circ$	$5^\circ$	$7^\circ$	$9^\circ$
D	8.60	*	9.29	0.339	*	0.366	$\theta_2$	$1^\circ$	$3^\circ$	$5^\circ$	$1^\circ$	$3^\circ$	$5^\circ$
E	9.95	*	10.26	0.392	*	0.404	DEP	0.05	0.10	0.20	0.002	0.004	0.008
e	2.54BSC			0.100BSC			$\Phi P1$	1.40	1.50	1.60	0.055	0.059	0.063
H	14.70	15.10	15.79	0.579	0.594	0.622							

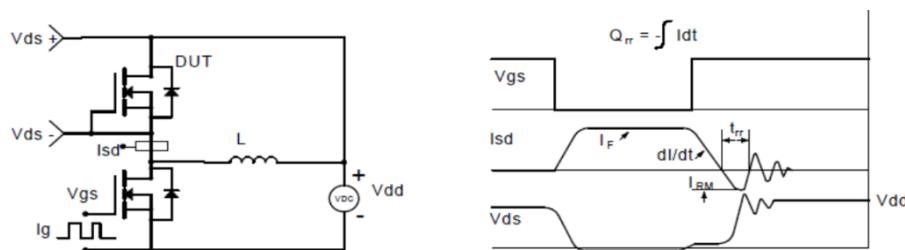
### Avalanche Test Circuit and Waveforms



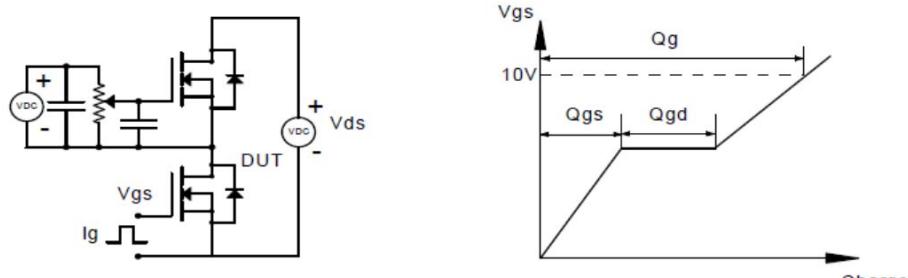
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



### Customer Service

Kwansemi Semiconductor Co.,Ltd

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